

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

ory / labs .01 Test ST - and Post-Stress ctrical Test	BZB84-C43-Q Part Description Nexperia DHAM SMD package Test Conditions Tamb = 25 °C JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85%	Zener Duration N/A 24 hours	# Lots	# Quantity	# Rejects
/ labs LO1 Test ST - and Post-Stress ctrical Test	Nexperia DHAM SMD package Test Conditions Tamb = 25 °C JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85%	Duration N/A			
.01 Test ST - and Post-Stress ctrical Test	SMD package Test Conditions Tamb = 25 °C JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85%	Duration N/A			
.01 Test ST - and Post-Stress ctrical Test	Test Conditions Tamb = 25 °C JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85%	N/A			
ST - and Post-Stress ctrical Test	Tamb = 25 °C JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85%	N/A			
- and Post-Stress ctrical Test	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85%	,	see below	all parts	aaa bala
ctrical Test	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85%	,	see below	all parts	aaa bala
	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85%	,	see below	all parts	aaa bala:::
	Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85%	24 hours			see below
	Soak Tamb = 85 °C, RH = 85%	24 hours			
conditioning		168 hours			
	Reflow soldering	3 cycles	1514	64430	0
	MIL-STD-750-1				
RB	M1038 Method A				
•	, , , , , , , , , , , , , , , , , , ,				
s	voltage	1000 hours	250	11400	0
	MIL-STD-750-1				
	M1038 Method B				
OP					
ady State Operational	reverse current	1000 hours	44	1920	0
nperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	311	14080	0
olased HAS I		96 hours	311	14080	0
	•				
ociave	Pressure = 205 kPa (29.7 psia)				
	JECD22 A101				
		10001	244	1 1000	
iiperature Keverse Blas		1000 nours	211	14080	0
1					
		1000	212	14120	0
ermittent Operating Life	100 °C for 15000 cycles	1000 nours	312	14120	0
н	IFSD22-Δ111				
		10 c	269	8070	0
	255 5 - 5 6	10.5	203	0070	· ·
	1-STD-002		10	6660	0
hs oa Thinh	n Temperature Reverse pp ady State Operational pperature Cycling AST iased HAST pclave TRB n Humidity High neerature Reverse Bias prmittent Operating Life	To Temperature Reverse voltage MIL-STD-750-1 M1038 Method B T j = Tjmax, Iz = 100% of max. datasheet reverse current MISSD22-A104 -65 °C to Tjmax, not to exceed 150°C AST JESD22-A118 Tamb = 130 °C, RH = 85 % JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia) FRB JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage [1] MIL-STD-750 Method 1037 ton = toff, devices powered to insure Δ Tj = trmittent Operating Life JESD22-A111 Stance to Solder Heat JESD22-A111 260 °C \pm 5 °C	Temperature Reverse Tj = Tjmax, VR = 80 % of rated reverse voltage 1000 hours	Temperature Reverse Tj = Tjmax, VR = 80 % of rated reverse voltage 1000 hours 250	Temperature Reverse Tj = Tjmax, VR = 80 % of rated reverse voltage 1000 hours 250 11400 MIL-STD-750-1 M1038 Method B Tj = Tjmax, Iz = 100% of max. datasheet reverse current 1000 hours 44 1920 JESD22-A104 -65 °C to Tjmax, not to exceed 150°C 1000 cycles 311 14080 AST JESD22-A118 Tamb = 130 °C, RH = 85 % 96 hours 311 14080 JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia) TRB JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^[1] 1000 hours 311 14080 MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = trmittent Operating Life 100 °C for 15000 cycles 100 s 269 8070

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Zener	11400	0	0,37	2,68E+09

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